# Handling

### All storage containers should be inspected per QA1008 Control Of Electrostatic Discharge (ESD) Procedure to use to ensure proper ESD protection.

### All containers should be clean and free of debris prior to use to mitigate the introduction of foreign object debris during the assembly process

#### All ESD amp cases must be cleaned and dried before re-using.

#### All gel packs (e.g. used for crystals) must be cleaned with scotch tape to remove dust and lint from gel surface.

### Machined parts should be transported in bin boxes, compartmented plastic containers or other applicable storage containers designed to mitigate damage to the product unless special handling requirements are called out on the router or purchase order.

### Parts cleaned per **TA1051** or **TA1061** prior to welding shall be loaded into covered ESD boxes by the assembly technicians. Parts too large for standard ESD boxes shall have critical welding surfaces protected by appropriate means. There is no requirement for the maximum amount of time allowed between the cleaning process and the welding process.

### Appropriate tweezers or finger cots are required for handling quartz or ceramic crystals so that the product is not handled by bare hands (oil residue can cause part contamination).

### NOTE: All finger cots must be ESD safe.

### Microelectronics parts/amplifiers must follow **QA1008 Control Of Electrostatic Discharge (ESD) Procedure**. All parts/amplifiers must be protected from physical damage, as well as ESD, when applied to production jobs.

### Lapped and Hydrogen Fired parts should be handled with tweezers or finger cots to preserve proper surface finish and to prevent part contamination

### Components that do not require special handling should be stored in and transported in bins, totes or protective wrapping to mitigate damage to the product.

### Hard coated parts should be stored in foam trays or other applicable foam packaging.

### Parts being sent to a vendor, such as Hydrogen fired, Hard coated, Anodized, Rokided and Flame Sprayed Parts can should be packed in foam and or applicable containers for transport.

### Any product components or sub-assemblies removed from a storage location with the PCB item number identified must remain under control of the same person until assembled to the product or returned to packaging or storage that clearly indicates the PCB item number.

# Storage

### All inventory, including point of use inventory that will become part of the product (including packaging and accessories), must be stored in packaging, containers or shelving that clearly indicate the PCB item number.

### Inventory shelf storage should be used for Machined, Purchased and sub-assemblies unless humidity and temperature controls are needed. See EN027 Nitrogen Storage List for those items that require humidity controlled storage.

### Sub-assemblies and parts that are susceptible to humidity are to be stored in one the following:

#### Store in Nitro: If component needs to be stored in Nitrogen to prevent oxidation and to prevent moisture absorption. (See EN027 for items that are stored in Nitrogen.) If only moisture absorption is a concern, the “store in desiccant” flag should be checked as stated in EN1006.

#### Store in Desiccant: If component needs to be stored in dry conditions to prevent moisture absorption from ambient humidity. Items with this flag may be stored in desiccant or Nitrogen.

### In process assemblies with epoxy curing or parts and assemblies that are susceptible to humidity are stored in ovens.

# Inventory

### PCB maintains a First In First Out (FIFO) inventory maintenance~~.~~

### Product can be assessed and visually inspected for damage or deterioration during cycle counting. Damaged or deteriorated products are handled per TA01 Nonconforming Material Control – Manufacturing Center.

### All Product (raw materials, sub assemblies, in-process and or finished goods) shall be dispatched and received into applicable storage areas by Inventory Control and Production Planning. The product, component or subassembly must be clearly marked with the proper PCB item number.

### If additional parts are needed due to scrap or re-work, Engineering and Production personnel should fill out Parts Request Tag and have Inventory Coordinator issue those parts.

### Short term part need for ENG or Production personnel which will be returned to inventory, can use the clipboard hanging in the inventory storage area to sign out a part. This is typically used when a part is being measured, shown, or for design input by Eng or Production Personnel. The clipboard should not be used for long term need. In that event the ENG or Production personnel should complete the parts request tag. This applies to 2nd and 3rd shifts.

# Control of RoHS Compliant Inventory

### Purchasing will be notified by Engineering that a RoHS compliant component needs to be ordered via the Business System Database (BSD).

### All inventory will be maintained per the requirements of this procedure with the following exception:

#### For RoHS compliant items where the vendor part # and PCB part # are not changing, and non-RoHS compliant parts will be on hand when the new parts are received, Purchasing, Planning and Engineering will review the current on hand quantity and demand for that item and make a decision on whether to use the parts up or scrap them out of the system.

### The Inventory group will be responsible for maintaining separate storage and (different locations) issue of these items with the goal of depleting non-RoHS components wherever applicable.